Dr Eu Poh Leng who is the Director of External Package Innovation in NXP Semiconductors, as well as the Vice Chairman of IEEE EPS Malaysia Chapter, was invited as a Keynote Speaker in the recent Symposium by Yole Development and NCAP on Advanced Packaging for Semiconductors (SYNAPS). In view of the Covid-19 pandemic situation, SYNAPS was held virtually for participants all over the world. The event took place over 3 half-days from 18th to 20th of May 2021, with 3 different categories of topic each day:

- Day 1: Heterogeneous Integration
- Day 2: Fan Out and SiP
- Day 3: Emerging Package and Performance

Dr Eu's sharing took place on Day 3, under the topic of “Advanced Packaging for Autonomous Driving”. Total 56 participants watched Dr Eu's presentation live, and 108 participants watched with the replay link. These participants are from > 20 companies worldwide, including Samsung Electronics, ERS Electronic GmbH, Hua Tian Leading Manufacturer, Fraunhofer, Applied Materials Inc., Besi, UTAC, TFME, SPTS Technologies, NCAP, On Semiconductor, ASM and so on. It was a very well-organized event with strong supports from semiconductor industry players internationally.